

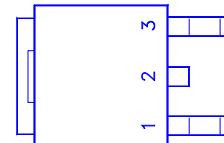
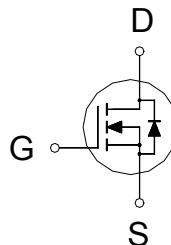
NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
TD422BL

TO-252

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	6mΩ	69A

**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS		UNITS
Gate-Source Voltage		V_{GS}	± 20		V
Continuous Drain Current ²	$T_C = 25^\circ\text{C}$	I_D	69		A
	$T_C = 100^\circ\text{C}$		45		
Pulsed Drain Current ¹		I_{DM}	180		
Avalanche Current		I_{AS}	41		
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	84		mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	50		W
	$T_C = 100^\circ\text{C}$		20		
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150		°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{θJC}$		2.5	°C / W

¹Pulse width limited by maximum junction temperature.²Package limitation current is 60A**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.2	1.7	2.8	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
On-State Drain Current ¹	$I_{D(\text{ON})}$	$V_{DS} = 10\text{V}, V_{GS} = 10\text{V}$	180			A

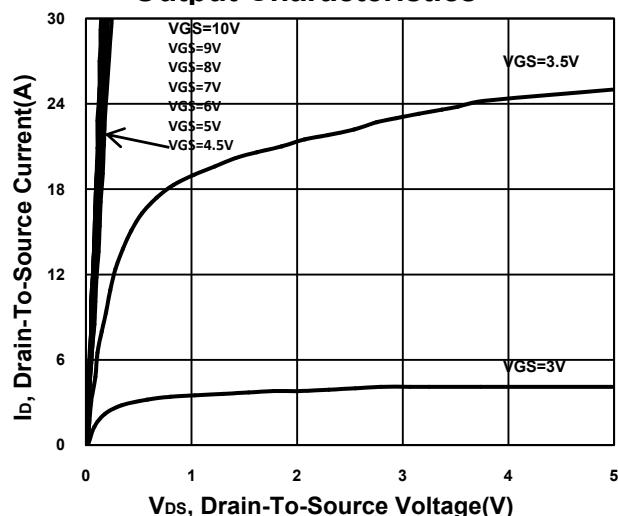
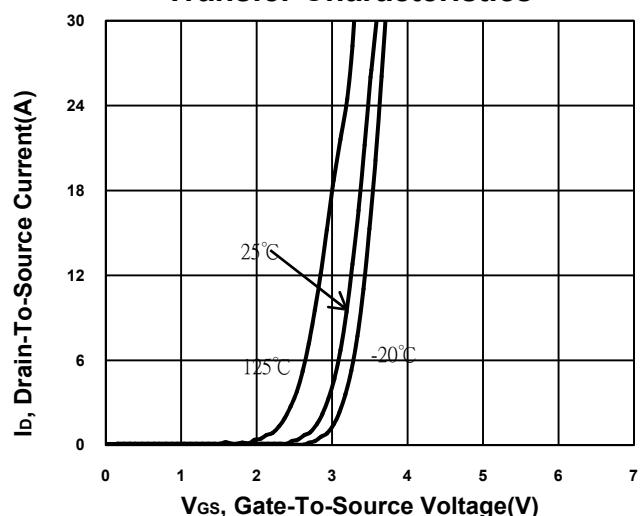
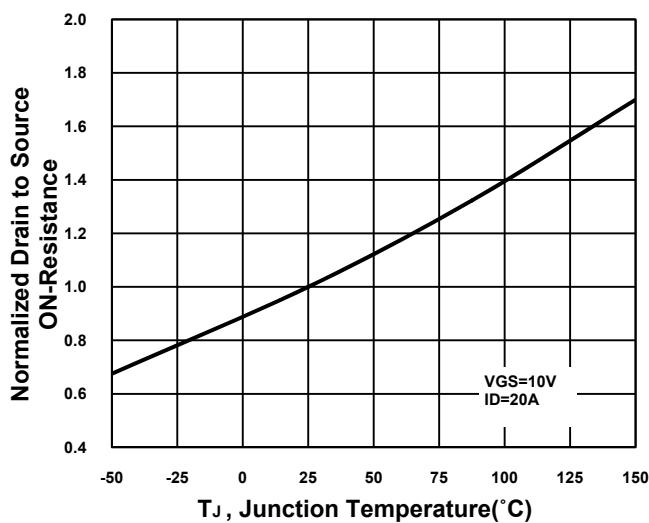
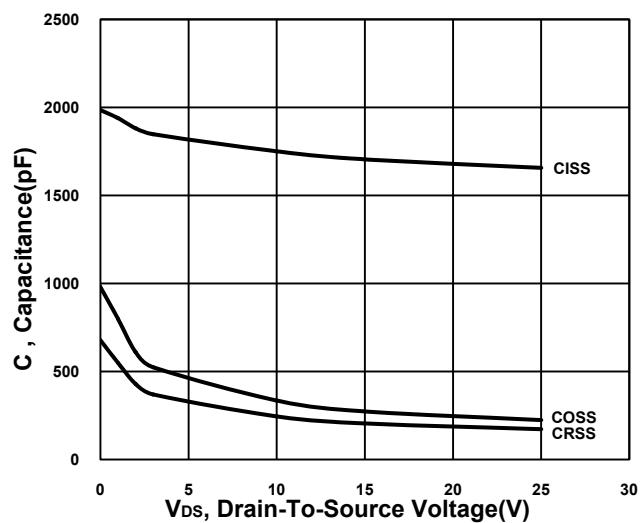
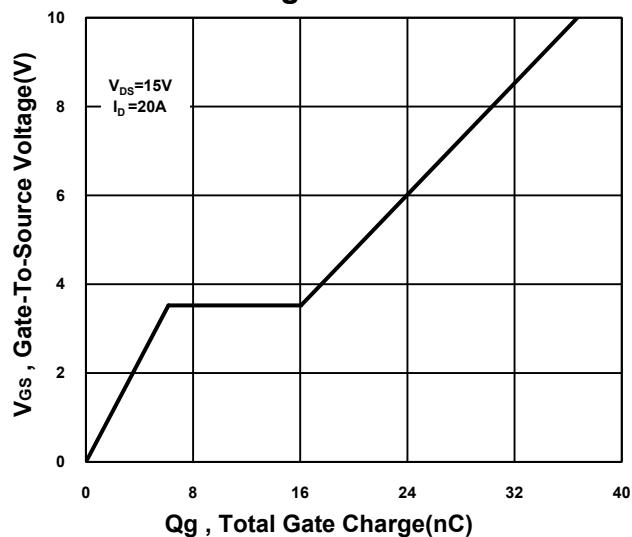
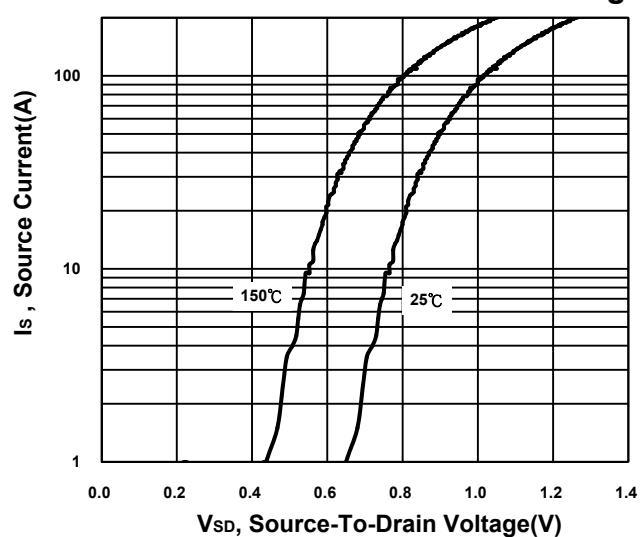
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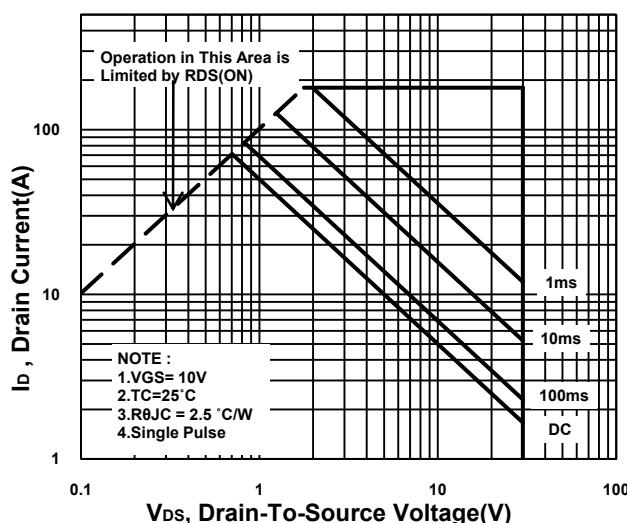
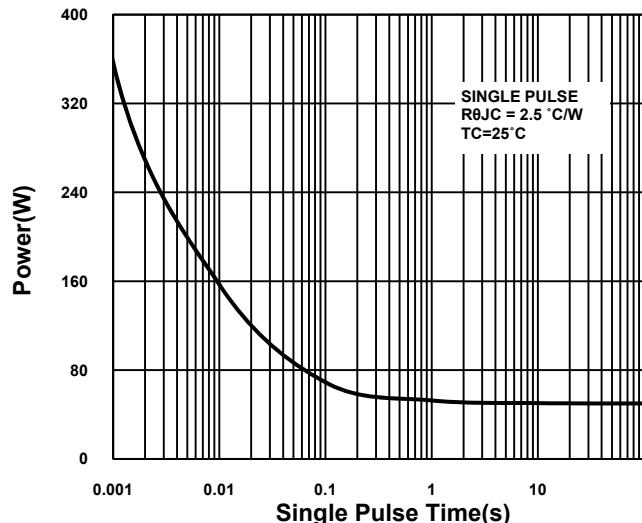
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Halogen-Free & Lead-Free

Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 20A$		7.8	9.5	$m\Omega$
		$V_{GS} = 10V, I_D = 20A$		4.6	6	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$		60		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		1850		pF
Output Capacitance	C_{oss}			270		
Reverse Transfer Capacitance	C_{rss}			230		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		1.1		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 15V, V_{GS} = 10V, I_D = 20A$		36.9		nC
Gate-Source Charge ²	Q_{gs}			6.3		
Gate-Drain Charge ²	Q_{gd}			10.5		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 15V, I_D \geq 20A, V_{GS} = 10V, R_{GEN} = 6\Omega$		22		nS
Rise Time ²	t_r			40		
Turn-Off Delay Time ²	$t_{d(off)}$			164		
Fall Time ²	t_f			85		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ³	I_S				69	A
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, dI_F/dt = 100A / \mu S$		30		nS
Reverse Recovery Charge	Q_{rr}			25		nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Package limitation current is 60A

NIKO-SEM**N-Channel Enhancement Mode
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Halogen-Free & Lead-Free**Output Characteristics****Transfer Characteristics****On-Resistance VS Temperature****Capacitance Characteristic****Gate charge Characteristics****Source-Drain Diode Forward Voltage**

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Halogen-Free & Lead-Free**Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**